

Preliminary Amendment

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Serial No.: Unknown

(International Application No. PCT/IB2004/000272)

Filed: Herewith

(International Filing Date: February 3, 2004)

Docket No.: I431.165.101

Title: SEMICONDUCTOR PACKAGE WITH HEAT SPREADER (as amended)

IN THE ABSTRACT

Please replace the Abstract with the following rewritten paragraph:

Abstract

1. A semiconductor package (1) is disclosed. In one embodiment the package includes comprises a semiconductor chip (2) including an active surface with a plurality of chip contact areas (3) and a package substrate (4) including a plurality of first contact areas (6) and a plurality of second contact areas (8) on its bottom surface. The chip (2) is mounted on the package substrate (4) with its active surface facing the package substrate (4). A plurality of conducting means (5) provide electrical contact between the chip contact areas (3) and the first contact areas (6). A heat spreading means (10) comprises a planar area (11) and at least one protrusion (12). The planar area (11) is attached to the upper surface of the chip (2) and the protrusion (12) is attached to the upper surface of the package substrate (4).

[Fig. 1]